

STN	Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy Časť 2-807: Skúšobné metódy na materiály na spájacie štruktúry Teplota rozkladu (T_d) pomocou TGA	STN EN IEC 61189-2-807 34 6513
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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-807: Test methods for materials for interconnection structures - Decomposition temperature (T_d) using TGA

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 12/21

Obsahuje: EN IEC 61189-2-807:2021, IEC 61189-2-807:2021

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EUROPEAN STANDARD

EN IEC 61189-2-807

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English Version

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-807: Test methods for materials for interconnection structures - Decomposition temperature (T_d) using TGA (IEC 61189-2-807:2021)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-807: Méthodes d'essai des matériaux pour structures d'interconnexion - Température de décomposition (T_d) par analyse thermogravimétrique (IEC 61189-2-807:2021)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-807: Prüfverfahren für Materialien für Verbindungsstrukturen - Zersetzungstemperatur (T_d) unter der Nutzung von TGA (IEC 61189-2-807:2021)

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Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-2-807:2021 (E)**European foreword**

The text of document 91/1697/CDV, future edition 1 of IEC 61189-2-807, prepared by IEC/TC 91 “Electronics assembly technology” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-807:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-07-08
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

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NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and-assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies		-
ISO 11358-1	-	Plastics - Thermogravimetry (TG) of polymers - Part 1: General principles	ofEN ISO 11358-1	-



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INTERNATIONAL STANDARD

NORME INTERNATIONALE

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Part 2-807: Test methods for materials for interconnection structures –
Decomposition temperature (T_d) using TGA**

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Partie 2-807: Méthodes d'essai des matériaux pour structures d'interconnexion – Température de décomposition (T_d) par analyse thermogravimétrique**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS
AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-807: Test methods for materials for interconnection structures –
Decomposition temperature (T_d) using TGA**

FOREWORD

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IEC 61189-2-807 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1697/CDV	91/1738/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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- withdrawn,
- replaced by a revised edition, or
- amended.

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-807: Test methods for materials for interconnection structures – Decomposition temperature (T_d) using TGA

1 Scope

This part of IEC 61189 specifies a test method to determine the decomposition temperature (T_d) of base laminate materials using thermogravimetric analysis (TGA).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194-2, *Printed boards design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies*

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